

CMOS 8-Bit Addressable Latch

High-Voltage Types (20-Volt Rating)

■ CD4099B 8-bit addressable latch is a serial-input, parallel-output storage register that can perform a variety of functions.

Data are inputted to a particular bit in the latch when that bit is addressed (by means of inputs A0, A1, A2) and when WRITE DISABLE is at a low level. When WRITE DISABLE is high, data entry is inhibited; however, all 8 outputs can be continuously read independent of WRITE DISABLE and address inputs.

A master RESET input is available, which resets all bits to a logic "0" level when RESET and WRITE DISABLE are at a high level. When RESET is at a high level, and WRITE DISABLE is at a low level, the latch acts as a 1-of-8 demultiplexer; the bit that is addressed has an active output which follows the data input, while all unaddressed bits are held to a logic "0" level.

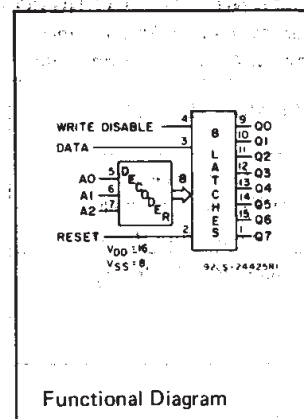
The CD4099B types are supplied in 16-lead hermetic ceramic dual-in-line packages (D and F suffixes), 16-lead plastic dual-in-line packages (E suffix), and in chip form (H suffix).

Features:

- Serial data input
- Active parallel output
- Storage register capability
- Master clear
- Can function as demultiplexer
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μ A at 18 V (full package-temperature range), 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) = 1 V at $V_{DD} = 5$ V, 2 V at $V_{DD} = 10$ V, 2.5 V at $V_{DD} = 15$ V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD}) -0.5V to +20V
Voltages referenced to V_{SS} Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to $V_{DD} + 0.5$ V
DC INPUT CURRENT, ANY ONE INPUT ± 10 mA
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW
For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearly at 12mW/ $^\circ\text{C}$ to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100mW
OPERATING-TEMPERATURE RANGE (T_A) -55°C to $+125^\circ\text{C}$
STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max $+265^\circ\text{C}$



Functional Diagram

Applications:

- Multi-line decoders
- A/D converters

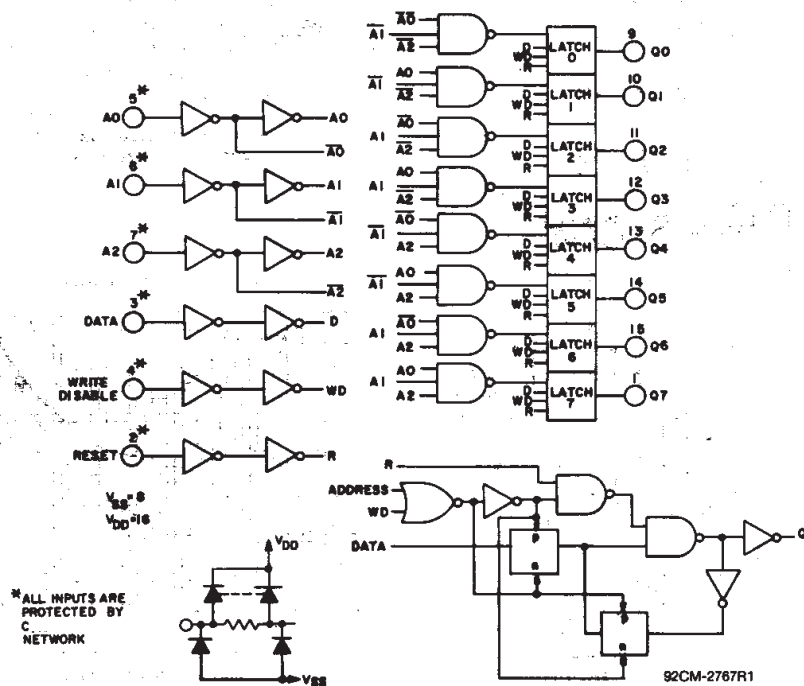
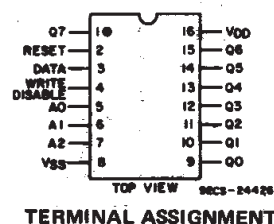


Fig. 1 — Logic diagram of CD4099B and detail of 1 of 8 latches.



TERMINAL ASSIGNMENT

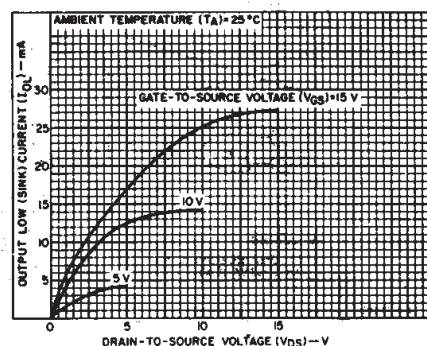


Fig. 2 — Typical output low (sink) current characteristics.

CD4099B Types

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ\text{C}$ (Unless otherwise specified)
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	SEE FIG. 15*	V _{DD} (V)	LIMITS		UNITS
			MIN.	MAX.	
Supply Voltage Range: (At T_A = Full Package Temperature Range)			3	18	V
Minimum Pulse Width, t_W Data	4	5	200	—	ns
		10	100	—	
		15	80	—	
Address	8	5	400	—	
		10	200	—	
		15	125	—	
Reset	5	5	150	—	
		10	75	—	
		15	50	—	
Setup Time, t_S Data to WRITE DISABLE	6	5	100	—	ns
		10	50	—	
		15	35	—	
Hold Time, t_H Data to WRITE DISABLE	7	5	150	—	ns
		10	75	—	
		15	50	—	

* Circled numbers refer to times indicated on master timing diagram.

Note: In addition to the above characteristics, a WRITE DISABLE ON time (the time that WRITE DISABLE is at a high level) must be observed during an address change for the total time that the external address lines A0, A1, and A2 are settling to a stable level, to prevent a wrong cell from being addressed (see Fig. 3).

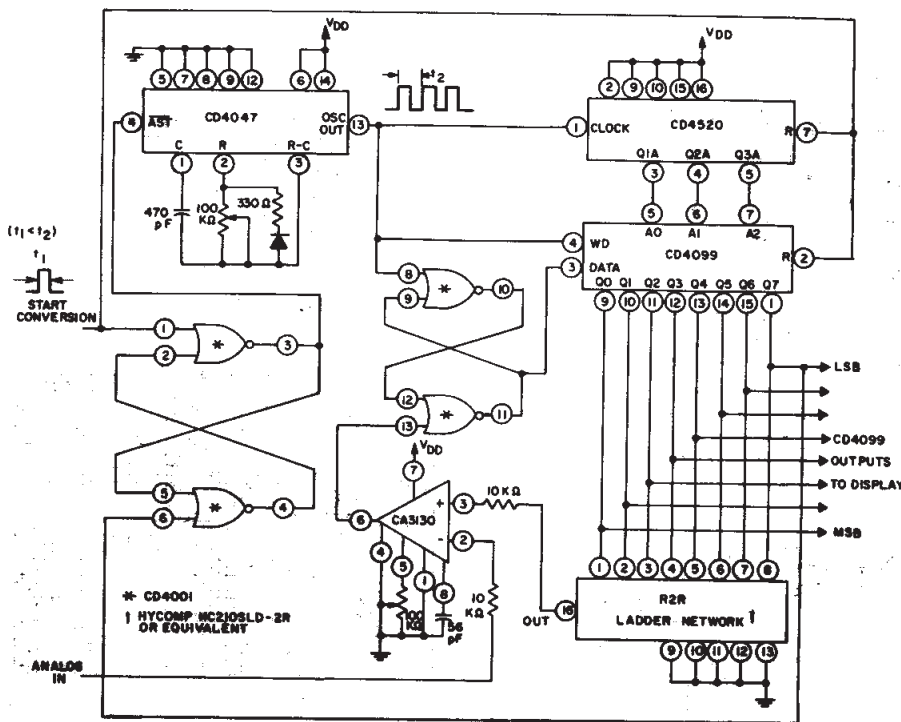


Fig. 5 — A/D converter

MODE SELECTION			
WD	R	ADDRESSED LATCH	UNADDRESSED LATCH
0	0	Follows Data	Holds Previous State
0	1	Follows Data (Active High 8-Channel Demultiplexer)	Reset to "0"
1	0	Holds Previous State	Reset to "0"
1	1	Reset to "0"	Reset to "0"

WD = WRITE DISABLE

R = RESET

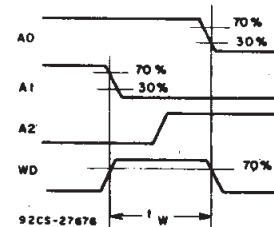


Fig. 3 — Definition of WRITE DISABLE ON time.

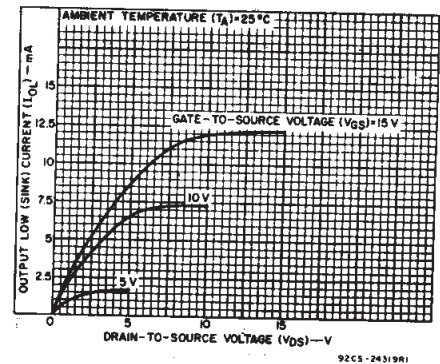


Fig. 4 — Minimum output low (sink) current characteristics.

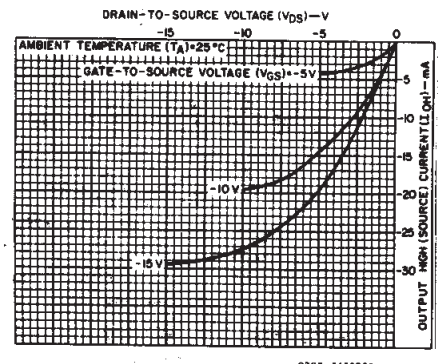
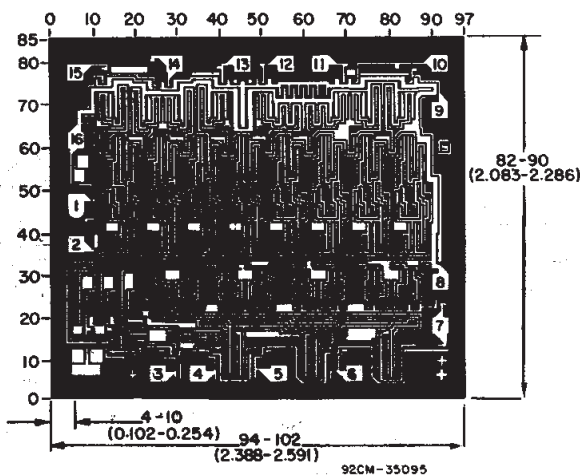


Fig. 6 — Typical output high (source) current characteristics.

CD4099B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)					+25			
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1, 9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1, 9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA



CD4099BH
DIMENSIONS AND PAD LAYOUT

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

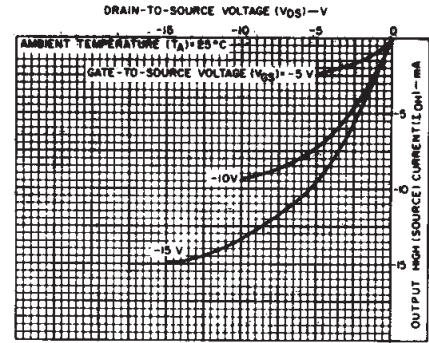


Fig. 7 — Minimum output high (source) current characteristics.

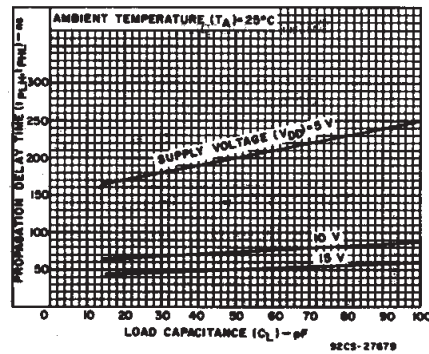


Fig. 8 — Typical propagation delay time (data to Q_n) vs. load capacitance.

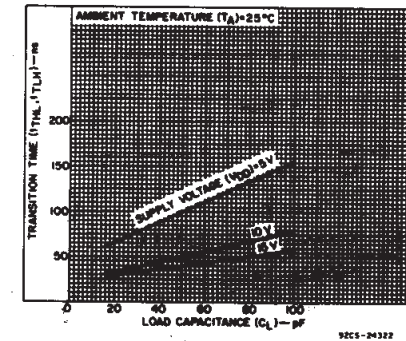


Fig. 9 — Typical transition time vs. load capacitance.

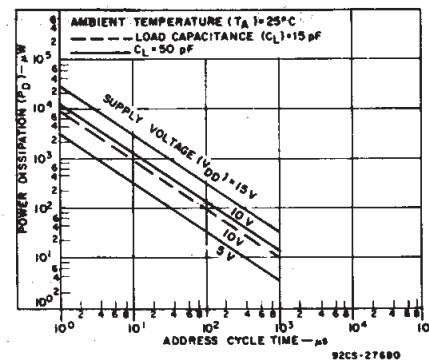


Fig. 10 — Typical dynamic power dissipation vs. address cycle time.

3
COMMERCIAL CMOS
HIGH VOLTAGE ICs

CD4099B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$,
Input $t_r, t_f = 20\text{ ns}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	SEE FIG.15*	V _{DD} (V)	LIMITS ALL PACKAGE TYPES		UNITS
			TYP.	MAX.	
Propagation Delay: t_{PLH} , t_{PHL}	①	5	200	400	ns
Data to Output,		10	75	150	
WRITE DISABLE		15	50	100	
to Output, t_{PLH} , t_{PHL}	②	5	200	400	
		10	80	160	
		15	60	120	
Reset to Output, t_{PHL}	③	5	175	350	ns
		10	80	160	
		15	65	130	
Address to Output, t_{PLH} , t_{PHL}	⑨	5	225	450	
		10	100	200	
		15	75	150	
Transition Time, (Any Output) t_{THL} , t_{TLH}		5	100	200	ns
		10	50	100	
		15	40	80	
Minimum Pulse Width, t_W	④	5	100	200	ns
Data		10	50	100	
		15	40	80	
Address	⑧	5	200	400	ns
		10	100	200	
		15	65	125	
Reset	⑤	5	75	150	ns
		10	40	75	
		15	25	50	
Minimum Setup Time, t_S	⑥	5	50	100	ns
Data to WRITE DISABLE		10	25	50	
		15	20	35	
Minimum Hold Time, t_H	⑦	5	75	150	ns
Data to WRITE DISABLE		10	40	75	
		15	25	50	
Input Capacitance, C_{IN}	Any Input		5	7.5	pF

*Circled numbers refer to times indicated on master timing diagram.

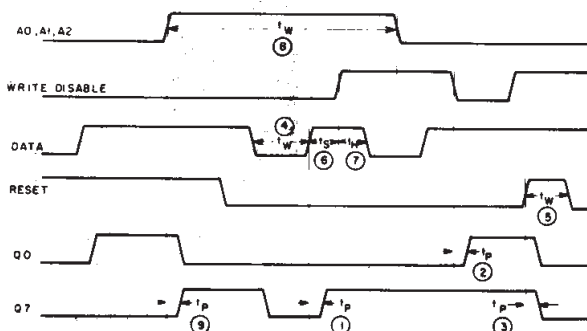


Fig. 15 — Master timing diagram.

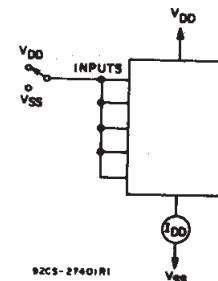


Fig. 11 — Quiescent device current test circuit.

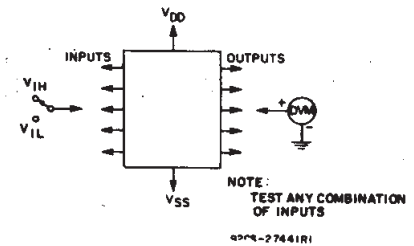


Fig. 12 — Input voltage test circuit.

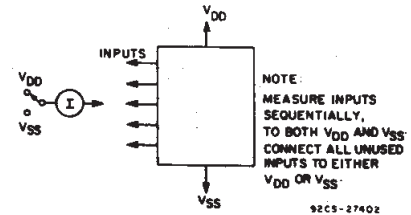


Fig. 13 — Input current test circuit.

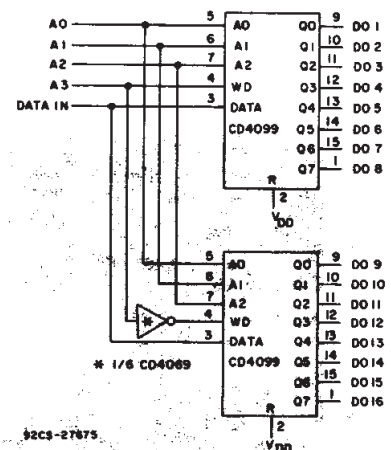


Fig. 14 — 1 of 16 decoder/demultiplexer.

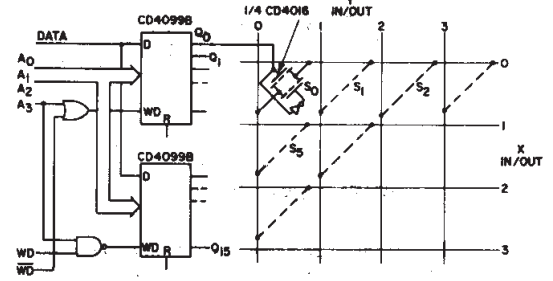


Fig. 16 — Multiple selection decoding — 4 x 4 crosspoint switch.

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